This document can handle board shapes up to 7.8in x 10in, although our panel vendors top out at 7in x 10in.

To re-size the board shape, do the following:
Select Lines on T-S Board Outline and delete lines in single layer mode: shift+space

Draw a rectangle using lines (example will be a 4 x 6 board)

Clear Place Line mode (keyboard p)
Keyboard j to jump to origin, hit enter
Keyboard j to jump to location, set x to 6000, hit enter twice
Keyboard j to jump to location, set x to 6000 and y to 4000, hit enter twice
Keyboard j to jump to location, set x to 0 and y to 4000, hit enter twice
Keyboard j to jump to origin, hit enter
Hit ESC twice to exit place line mode

Select Lines on T-S Board Outline
Menu Design/Board Shape/Define Free Selected Objects (keyboard d)
To define a KeepOut that surrounds the board outlines
Menu Design/Board Shape/Create Rectangles From Board Shape (keyboard d)
Set the KeepOut Layer as the layer, pull up as preferred

Draw Route Tool Outline is selected, hit enter

If you resize the board, don’t forget to move the drill table strings on the Drill Drawing Layer…they should be just to the right of your board shape.
<table>
<thead>
<tr>
<th>Symbol</th>
<th>Hit Count</th>
<th>Tool Size</th>
<th>Plated Hole Type</th>
</tr>
</thead>
<tbody>
<tr>
<td>001</td>
<td>12</td>
<td>0.050</td>
<td>PTH Round</td>
</tr>
<tr>
<td>002</td>
<td>11</td>
<td>0.050</td>
<td>PTH Round</td>
</tr>
<tr>
<td>003</td>
<td>112</td>
<td>0.050</td>
<td>PTH Round</td>
</tr>
<tr>
<td>004</td>
<td>2</td>
<td>0.050</td>
<td>PTH Round</td>
</tr>
<tr>
<td>005</td>
<td>2</td>
<td>0.050</td>
<td>PTH Round</td>
</tr>
<tr>
<td>006</td>
<td>0</td>
<td>0.050</td>
<td>PTH Round</td>
</tr>
<tr>
<td>007</td>
<td>4</td>
<td>0.050</td>
<td>PTH Round</td>
</tr>
</tbody>
</table>

449 Total
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